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PRODUCT SPECIFICATION

Grad Conn Part No.: CH03-AG

Product Description: Sim Card Holder SMT Slid In Type With Fixed Cover

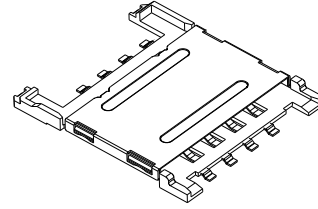
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1. INTRODUCTION

General:

The CH03-AG is an interface device for GSM 11.11 SIM card. It is designed for high performance and flexibility to give prospective customers a quick applications of the individual devices in their product series, and to facilitate selection if the device it decides that are best-suited to intended target applications.



Features:

- ◆ GSM 11.11 Standard SIM Card. ^(note)
- ◆ Ultra Slim (H = 1.60 mm)
- ◆ Compact Physical Size for Multi-Purpose Application.
- ◆ High Reliability Low-Friction Contact Extension operation Life of Contact.
- ◆ RoHS Directive 2002/95/EC Compliant.

Applications:

- ◆ Access Control Terminals.
- ◆ Terminal Identification module.
- ◆ Telecommunication.
- ◆ Palm Top Machines.
- ◆ Other Identification recognition.

Note: All trademarks mentioned herein are the property of their respective companies.

2. TECHNICAL CHARACTERISTICS

2.1 General Characteristics:

| Items | Standard | Description |
|--------------------|-----------|------------------------------|
| Dimension | | 19.15L x 16.50W x 1.60H mm |
| Weight | | Approx. 0.42 g |
| Card size | GSM 11.11 | 25.0 x 15.0 x 0.76 mm |
| Contact principle | | Friction technology |
| Operating position | | Shaft up / Down / Horizontal |
| Mounting System | | SMT Type (without post) |
| Durability | | 5,000 cycles min. |

2.2 Electrical Characteristics: According to Standard IEC512

| Items | Standard | Description |
|----------------------------------|-------------|---------------------------------|
| Number of contacts | | 6, 8 pins (optional) |
| Contact resistance | IEC512-2-2a | 50 mΩ typical, 100 mΩ max. |
| Insulation resistance Pin to pin | IEC512-2-3a | > 1000 MΩ / 500 V DC |
| Rated voltage | | 30 V max. |
| Rated current | | 1 A max. |
| Dielectric withstanding voltage | IEC512-2-4a | 500 V AC rms 1 min. (sea level) |

2.3 Mechanical Characteristics:

| Items | Standard | Description |
|---------------------|-----------------|-------------------------|
| Contact force | SIM Card 0.76mm | 0.4N ~ 1.0N |
| Contact location | GSM 11.11 | |
| Data Contacts | | |
| Material | | Phosphor bronze |
| Plating | | Gold over Nickel |
| Insulation material | | Thermoplastic, UL 94V-0 |
| Cover material | | Stainless Steel |

2.4 Solderability: According to Standard IEC68

| Items | Standard | Description |
|------------------|------------|---------------------|
| Wave | | Not applicable |
| IR reflow | | 260°C, 10 sec. Max. |
| Manual soldering | IEC68-2-20 | 360°C, 3 sec. Max. |

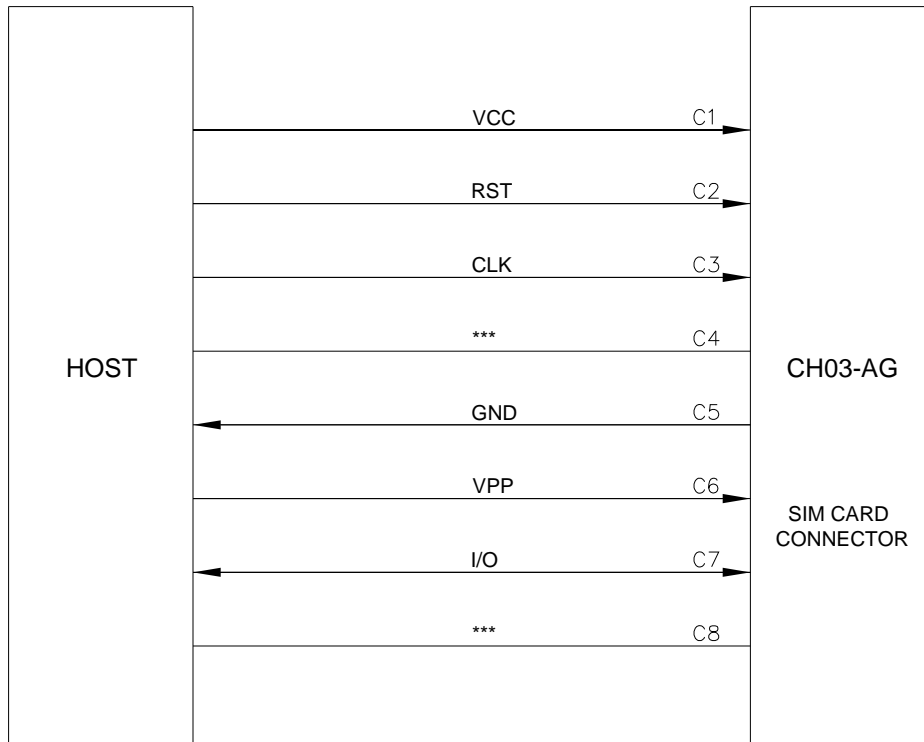
2.5 Environmental Characteristics: According to Standard IEC68

| Items | Standard | Description |
|-----------------------|----------|-----------------|
| Operating temperature | | - 40°C ~ + 85°C |
| Operating humidity | | 10 % ~ 95 % RH |
| Storage temperature | | - 40°C ~ + 85°C |
| Storage humidity | | 10 % ~ 95 % RH |

3. ORDERING CODE

| Part Number | Number of Contacts | PCB Locating Pegs (Post) | Logo |
|----------------|--------------------|--------------------------|------|
| CH03-AG060-0BR | 6 | No | No |
| CH03-AG080-0BR | 8 | No | No |

4. INTERFACE

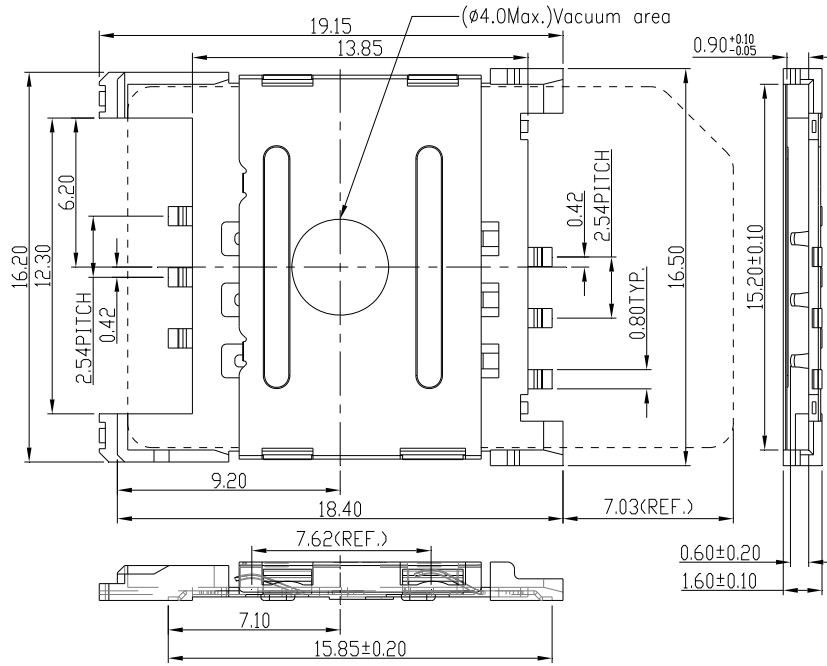


4.1 Signals

Signal interface connections for CH03-AG are shown below.

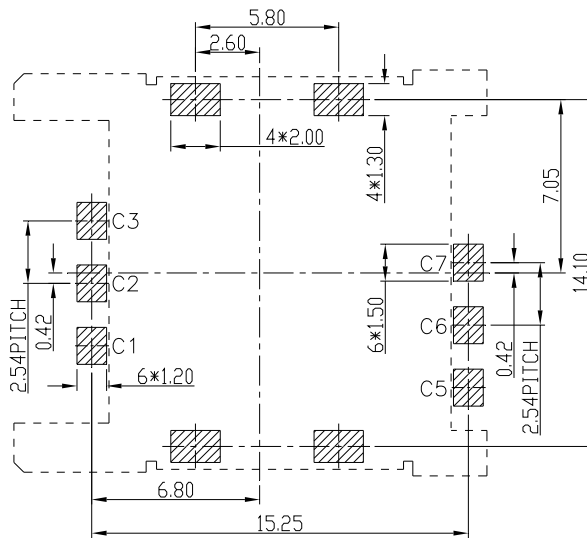
| Contact No. | Assignment | Description | Remark |
|-------------|------------|--------------------------|--------|
| C1 | VCC | Power Voltage | |
| C2 | RST | Reset Signal | |
| C3 | CLK | Clocking Signal | |
| C4 | *** | Reserved for feature use | |
| C5 | GND | Power and Signal Ground | |
| C6 | VPP | Programming Voltage | |
| C7 | I/O | Serial Data input/output | |
| C8 | *** | Reserved for feature use | |

5. MECHANICAL OUTLINE DRAWING



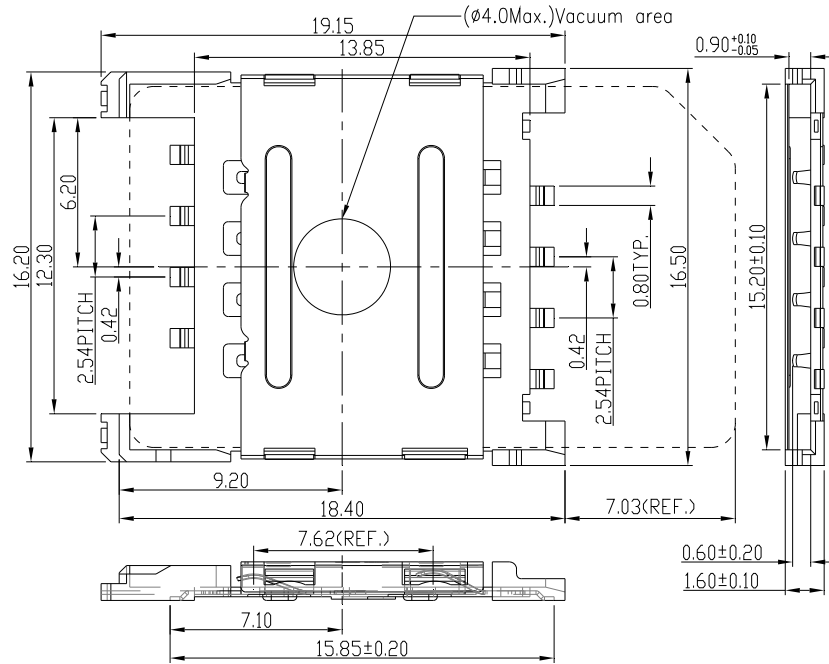
Unit: mm; Tolerances: ±0.15 mm

Figure 5.1 Mechanical outline dimension (6 pins)



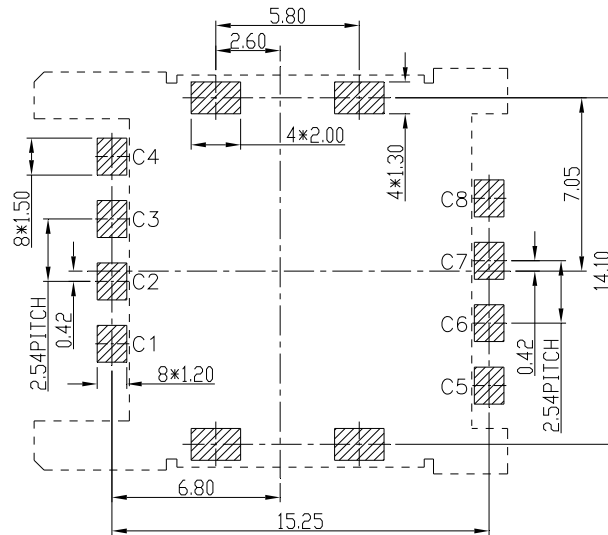
Unit: mm; Tolerances: ±0.05 mm

Figure 5.2 Reference dimension for PCB layout (6 pins)



Unit: mm; Tolerances: ±0.15 mm

Figure 5.3 Mechanical outline dimension (8 pins)

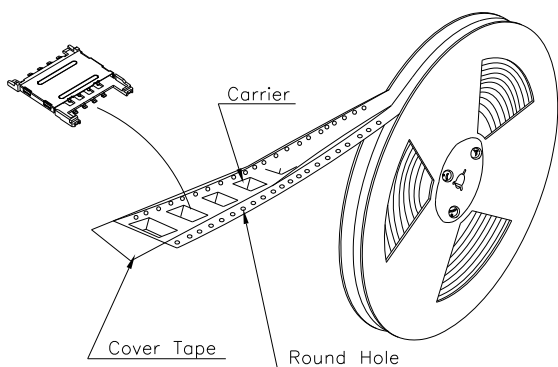


Unit: mm; Tolerances: ±0.05 mm

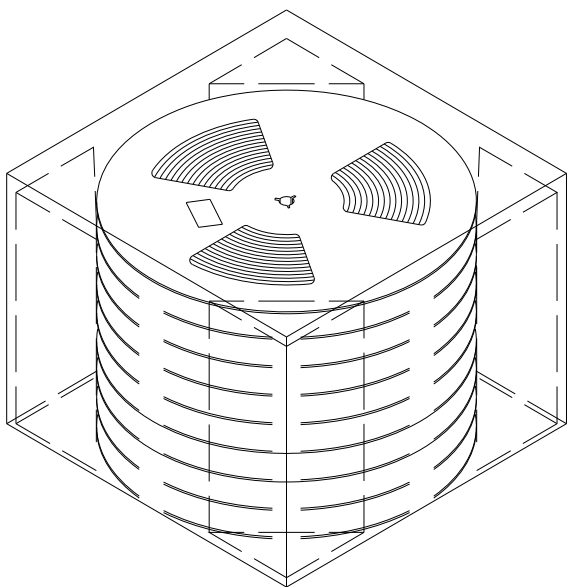
Figure 5.4 Reference dimension for PCB layout (8 pins)

APPENDIX A: PACKING INFORMATION

A1: Carrier Tape (Meet EIA-481 Standard)



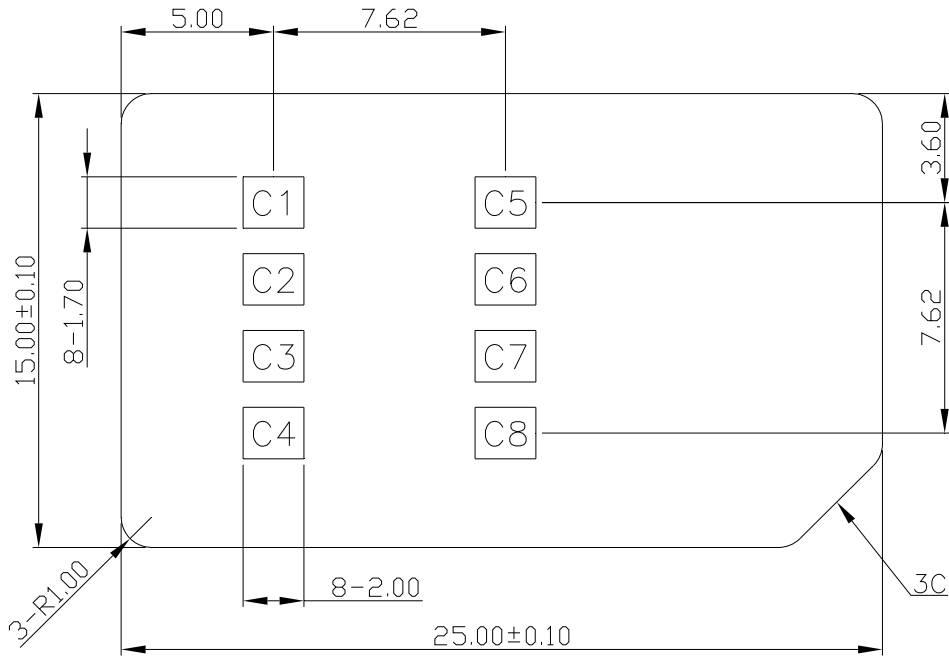
N.W.: 0.42 KGS
G.W.: 0.97 KGS
Q'TY: 1,000 PCs per reel
Meas.: dia. 33 CM, W3.2 CM



N.W.: 3.36 KGS
G.W.: 8.96 KGS
Q'TY: 8,000 PCs per carton
(8 reels set in order)
Meas.: 35.0L x 35.0W x 32.5H CM

APPENDIX B: SIM CARD DIMENSION (According to Standard GSM 11.11)

Dimensions in millimeters (mm)



Thickness: 0.76 +/- 0.08 mm